


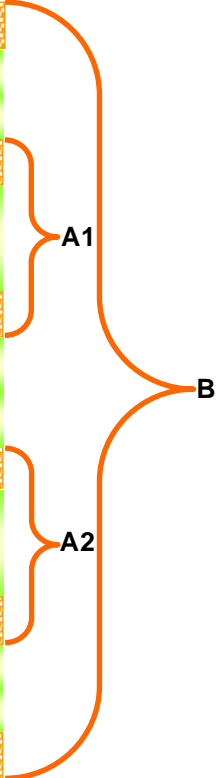







**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

**06 151 FR4 55 L41.35 P10\_06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_151\_FR4\_55\_L41.35\_p10\_06**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	55 $\mu$	Copper		
	60 $\mu$	Prepreg		
<b>Layer-2</b>	60 $\mu$	Prepreg		
	35 $\mu$	Copper		
<b>Layer-3</b>	410 $\mu$	L-FR4		
	35 $\mu$	Copper		
<b>Layer-4</b>	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-5</b>	35 $\mu$	Copper		
	410 $\mu$	L-FR4		
<b>Layer-99</b>	60 $\mu$	Prepreg		
	60 $\mu$	Prepreg		
	55 $\mu$	Copper		

© Copyright by Printed Circuit Boards GmbH